

IN THE CLAIMS

1. (Original) A semiconductor device, comprising:
an integrated circuit chip;
a base to which said integrated circuit chip is
mounted and connected;
a plurality of terminals disposed on said base for
connection of said integrated circuit chip to the outside;
a plurality of metal bumps one formed on each of
said plurality of terminals; and
a supporting frame for fixedly supporting said
integrated circuit chip or said base,
wherein said base includes a circuit board or a
circuit film having a circuit pattern formed on an insulating
base.

Claims 2-34 (Canceled)